

Flash Erasable, Reprogrammable CMOS PAL® Device

Features

- Advanced second-generation PAL architecture
- Low power
 - 90 mA max. commercial (10 ns)
 - 130 mA max, commercial (7.5 ns)
- CMOS Flash EPROM technology for electrical erasability and reprogrammability
- Variable product terms
 - -2 x (8 through 16) product terms
- User-programmable macrocell
 - Output polarity control
 - Individually selectable for registered or combinatorial operation
- Up to 22 input terms and 10 outputs

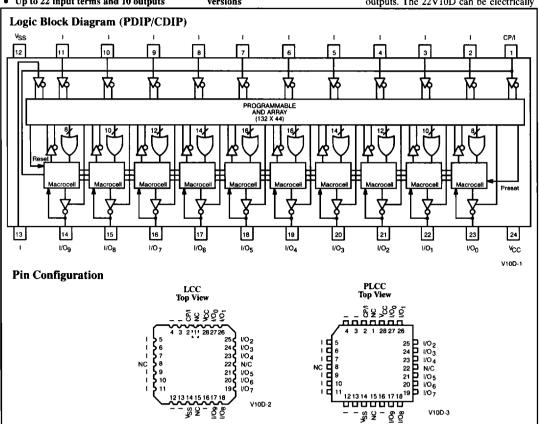
- DIP, LCC, and PLCC available
 - 7.5 ns commercial version
 - 5 ns t_{CO}
 - 5 ns ts
 - 7.5 ns tpD
 - 133-MHz state machine
 - 10 ns military and industrial ver-
 - 6 ns t_{CO}
 - 6 ns ts
 - 10 ns t_{PD}
 - 110-MHz state machine
- 15-ns commercial and military
- 25-ns commercial and military versions

- High reliability
 - Proven Flash EPROM technology
 - 100% programming and functional testing

Functional Description

The Cypress PALC22V10D is a CMOS Flash Erasable second-generation programmable array logic device. It is implemented with the familiar sum-of-products (AND-OR) logic structure and the programmable macrocell.

The PALC22V10D is executed in a 24-pin 300-mil molded DIP, a 300-mil cerDIP, a 28-lead square ceramic leadless chip carrier, a 28-lead square plastic leaded chip carrier, and provides up to 22 inputs and 10 outputs. The 22V10D can be electrically



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Functional Description (continued)

erased and reprogrammed. The programmable macrocell provides the capability of defining the architecture of each output individually. Each of the 10 potential outputs may be specified as "registered" or "combinatorial." Polarity of each output may also be individually selected, allowing complete flexibility of output configuration. Further configurability is provided through "array" configurable "output enable" for each potential output. This feature allows the 10 outputs to be reconfigured as inputs on an individual basis, or alternately used as a combination I/O controlled by the programmable array.

PALC22V10D features a variable product term architecture. There are 5 pairs of product term sums beginning at 8 product terms per output and incrementing by 2 to 16 product terms per output. By providing this variable structure, the PALC 22V10D is optimized to the configurations found in a majority of applications without creating devices that burden the product term structures with unusable product terms and lower performance.

Additional features of the Cypress PALC22V10D include a synchronous preset and an asynchronous reset product term. These product terms are common to all macrocells, eliminating the need to dedicate standard product terms for initialization functions. The device automatically resets upon power-up.

The PALC22V10D, featuring programmable macrocells and variable product terms, provides a device with the flexibility to implement logic functions in the 500- to 800-gate-array complexity. Since each of the 10 output pins may be individually configured as inputs on a temporary or permanent basis, functions requiring up to 21 inputs and only a single output and down to 12 inputs and 10 outputs are possible. The 10 potential outputs are enabled using

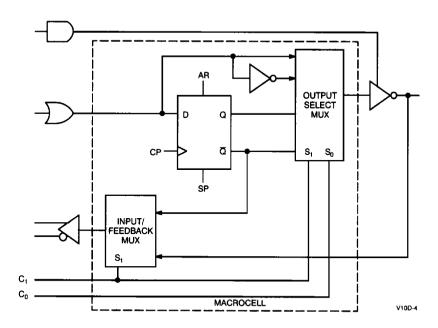
product terms. Any output pin may be permanently selected as an output or arbitrarily enabled as an output and an input through the selective use of individual product terms associated with each output. Each of these outputs is achieved through an individual programmable macrocell. These macrocells are programmable to provide a combinatorial or registered inverting or non-inverting output. In a registered mode of operation, the output of the register is fed back into the array, providing current status information to the array. This information is available for establishing the next result in applications such as control state machines. In a combinatorial configuration, the combinatorial output or, if the output is disabled, the signal present on the I/O pin is made available to the array. The flexibility provided by both programmable product term control of the outputs and variable product terms allows a significant gain in functional density through the use of programmable logic.

Along with this increase in functional density, the Cypress PALC22V10D provides lower-power operation through the use of CMOS technology, and increased testability with Flash reprogrammability.

Configuration Table

	Registered/Combinatorial						
C ₁ C ₀ Configuration							
0 0 Registered/Active LOW							
0	1	Registered/Active HIGH					
1	0	Combinatorial/Active LOW					
1	11	Combinatorial/Active HIGH					

Macrocell





Maximum Ratings (Above which the useful life may be impaired. For user guidelines, not tested.)

(Above which the dictal me may be imparted. For dict guidem
Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage to Ground Potential (Pin 24 to Pin 12) $-0.5V$ to $+7.0V$
DC Voltage Applied to Outputs in High Z State0.5V to +7.0V
DC Input Voltage0.5V to +7.0V
Output Current into Outputs (LOW) 16 mA
DC Programming Voltage 12.5V
Latch-Up Current

Static Discharge Voltage	
Static Discharge Voltage (per MIL-STD-883, Method 3	3015) > 2001V

Operating Range

Range	Ambient Temperature	v _{cc}
Commercial	0°C to +75°C	5V ±5%
Military ^[1]	-55°C to +125°C	5V ±10%
Industrial	-40°C to +85°C	5V ±10%

Electrical Characteristics Over the Operating Range[2]

Parameter	Description		Test Conditions		Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min.$	$I_{OH} = -3.2 \text{ mA}$	Com'l	2.4		ν
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -2 \text{ mA}$	Mil/Ind			
V_{OL}	Output LOW Voltage	$V_{CC} = Min.,$ $V_{IN} = V_{IH} \text{ or } V_{II}.$	$I_{OL} = 16 \text{ mA}$	Com'i		0.5	v
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 12 mA	Mil/Ind			
V_{lH}	Input HIGH Level	Guaranteed Input Lo	gical HIGH Voltage	for All Inputs[3]	2.0		v
$V_{IL}^{[4]}$	Input LOW Level	Guaranteed Input Lo	Guaranteed Input Logical LOW Voltage for All Inputs[3]				V
I _{IX}	Input Leakage Current	$V_{SS} \leq V_{IN} \leq V_{CC}$, V	$V_{SS} \le V_{1N} \le V_{CC}, V_{CC} = Max.$				
I _{OZ}	Output Leakage Current	V_{CC} = Max., $V_{SS} \le$	-40	40	μА		
I _{SC}	Output Short Circuit Current	V_{CC} = Max., V_{OUT}	-30	-90	mA		
I _{CC1}	Standby Power Supply Current	$V_{CC} = Max.,$	10, 15, 25 ns	Com'l		90	mA
	Current	V _{IN} = GND, Outputs Open in	7.5 ns	1 [130	mA
		Unprogrammed Device	15, 25 ns	Mil/Ind		120	mA
			10 ns	1 [120	mA
I _{CC2} ^[6]	Operating Power Supply	$V_{CC} = Max., V_{IL} = 0V, V_{IH} = 3V,$	10, 15, 25 ns	Com'l		110	mA
	Current	Output Open, De-	7.5 ns	1 1		140	mA
		vice Programmed as a 10-Bit Counter,	15, 25 ns	Mil/Ind		130	mA
		f = 25 MHz	10 ns	7 t		130	mA

Capacitance^[6]

Parameter	Description	Test Conditions	Min.	Max.	Unit
C _{IN}	Input Capacitance	$V_{IN} = 2.0V @ f = 1 MHz$		10	pF
COUT	Output Capacitance	$V_{OUT} = 2.0V @ f = 1 MHz$		10	pF

Endurance Characteristics[6]

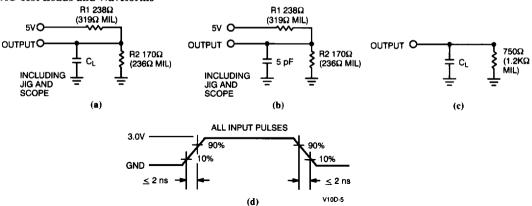
Parameter	Description	Test Conditions	Min.	Max.	Unit
N	Minimum Reprogramming Cycles	Normal Programming Conditions	100		Cycles

Notes:

- TA is the "instant on" case temperature.
- See the last page of this specification for Group A subgroup testing information.
- These are absolute values with respect to device ground. All overshoots due to system or tester noise are included.
- 4. V_{IL} (Min.) is equal to -3.0V for pulse durations less than 20 ns.
- Not more than one output should be tested at a time. Duration of the short circuit should not be more than one second. $V_{\rm OUT}=0.5V$ has been chosen to avoid test problems caused by tester ground degradation.
- Tested initially and after any design or process changes that may affect these parameters.



AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT (Commercial)

Equivalent to:	THÉVENIN EQUIV	ALENT (Military)
OUTPUT O	136Ω	2.13V = V _{thm}

Load Speed	C _L	Package
7.5, 10, 15, 25 ns	50 pF	PDIP, CDIP, PLCC, LCC

Parameter	V _X	Output Waveform—Measurement Level
t _{ER} (-)	1.5V	V _{OH} 0.5V V _X v _{10D-8}
t _{ER (+)}	2.6V	V _{OL} 0.5V V _X
t _{EA (+)}	0V	V _X 1.5V V _{OH} V _{10D-10}
t _{EA (-)}	V _{thc}	V _X 0.5V V _{OL. V10D-11}

(e) Test Waveforms



Commercial Switching Characteristics PALC22V10D[2,7]

		22V1	0D-7	22V10D-10		22V10D-15		22V10D-25		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
t _{PD}	Input to Output Propagation Delay ^[8, 9]	3	7.5	3	10	3	15	3	25	ns
t _{EA}	Input to Output Enable Delay[10]		8		10		15		25	ns
t _{ER}	Input to Output Disable Delay[11]		8		10		15		25	ns
t _{CO}	Clock to Output Delay[8, 9]	2	5	2	7	2	8	2	15	ns
t _{S1}	Input or Feedback Set-Up Time	5		6		10		15		ns
t _{S2}	Synchronous Preset Set-Up Time	6		7		10		15		ns
t _H	Input Hold Time	0		0		0		0		ns
tp	External Clock Period (t _{CO} + t _S)	10		12		20		30		ns
t _{WH}	Clock Width HIGH ^[6]	3		3		6		13		ns
t _{WL}	Clock Width LOW[6]	3		3		6		13		ns
f _{MAX1}	External Maximum Frequency (1/(t _{CO} + t _S)) ^[12]	100		76.9		55.5		33.3		MHz
f _{MAX2}	Data Path Maximum Frequency (1/(t _{WH} + t _{WL})) ^[6, 13]	166		142		83.3		35.7		MHz
f _{MAX3}	Internal Feedback Maximum Frequency (1/(t _{CF} + t _S)) ^[6, 14]	133		111		68.9		38.5		MHz
t _{CF}	Register Clock to Feedback Input ^[6, 15]		2.5		3		4.5		13	ns
t _{AW}	Asynchronous Reset Width	8		10		15		25		ns
t _{AR}	Asynchronous Reset Recovery Time	5		6		10		25		ns
t _{AP}	Asynchronous Reset to Registered Output Delay		12		13		20		25	ns
t _{SPR}	Synchronous Preset Recovery Time	6		8		10		15		ns
tpR	Power-Up Reset Time ^[6, 16]	1		1		1		1		μs

Notes:

- Notes:

 Part (a) of AC Test Loads and Waveforms is used for all parameters except t_{ER} and t_{EA(+)}. Part (b) of AC Test Loads and Waveforms is used for t_{ER}. Part (c) of AC Test Loads and Waveforms is used for t_{EA(+)}.
- Min.t imes are tested initially and after any design or process changes that may affect these parameters.
- 9. This specification is guaranteed for all device outputs changing state in a given access cycle.
- 10. The test load of part (a) of AC Test Loads and Waveforms is used for measuring t_{EA(-)}. The test load of part (c) of AC Test Loads and Waveforms is used for measuring t_{EA(+)} only. Please see part (e) of AC Test Loads and Waveforms for enable and disable test waveforms and measurement reference levels.
- 11. This parameter is measured as the time after output disable input that the previous output data state remains stable on the output. This delay is measured to the point at which a previous HIGH level has fallen to 0.5 volts below V_{OH} min. or a previous LOW level has risen to 0.5 volts above V_{OL} max. Please see part (e) of AC Test Loads and Waveforms for enable and disable test waveforms and measurement reference levels.
- This specification indicates the guaranteed maximum frequency at which a state machine configuration with external feedback can operate.
- This specification indicates the guaranteed maximum frequency at which the device can operate in data path mode.
- This specification indicates the guaranteed maximum frequency at which a state machine configuration with internal only feedback can operate.
- This parameter is calculated from the clock period at f_{MAX} internal (1/f_{MAX3}) as measured (see Note 11 above) minus t_S.
- 16. The registers in the PALC22V10D have been designed with the capa-

must be monotonic and the timing constraints depicted in Power-Up Reset Waveform must be satisfied.

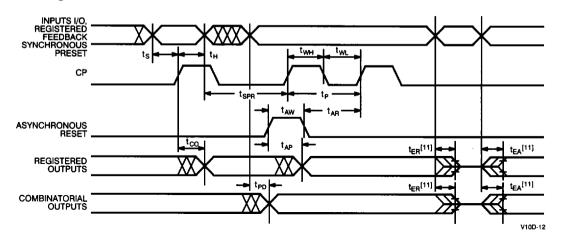


Military and Industrial Switching Characteristics PALC22V10D[2,7]

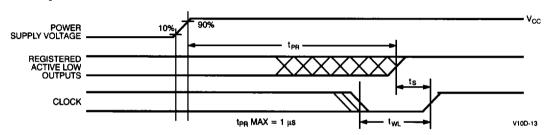
		22V10	DD-10	22V1	DD-15	22V10D-25		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit
t _{PD}	Input to Output Propagation Delay ^[8, 9]	3	10	3	15	3	25	ns
t _{EA}	Input to Output Enable Delay[10]		10		15	1	25	ns
ter	Input to Output Disable Delay[11]		10		15		25	ns
t _{CO}	Clock to Output Delay[8, 9]	2	7	2	8	2	15	ns
t _{S1}	Input or Feedback Set-Up Time	6		10		18		ns
t _{S2}	Synchronous Preset Set-Up Time	7		10		18		ns
t _H	Input Hold Time	0		0		0		ns
tp	External Clock Period (t _{CO} + t _S)	12		20		33		ns
t _{WH}	Clock Width HIGH ^[6]	3		6		14		ns
twL	Clock Width LOW ^[6]	3		6		14		ns
f _{MAX1}	External Maximum Frequency (1/(t _{CO} + t _S)) ^[12]	76.9		50.0		30.3		MHz
f _{MAX2}	Data Path Maximum Frequency $(1/(t_{WH} + t_{WL}))^{[6, 13]}$	142		83.3		35.7		MHz
f _{MAX3}	Internal Feedback Maximum Frequency (1/(t _{CF} + t _S)) ^[6, 14]	111		68.9		32.2		MHz
t _{CF}	Register Clock to Feedback Input ^[6, 15]		3		4.5		13	ns
t _{AW}	Asynchronous Reset Width	10		15		25	-	ns
t _{AR}	Asynchronous Reset Recovery Time	6		12		25		ns
t _{AP}	Asynchronous Reset to Registered Output Delay	_	12		20		25	ns
t _{SPR}	Synchronous Preset Recovery Time	8		20		25		ns
t _{PR}	Power-Up Reset Time[6, 16]	1		1		1		μs



Switching Waveform

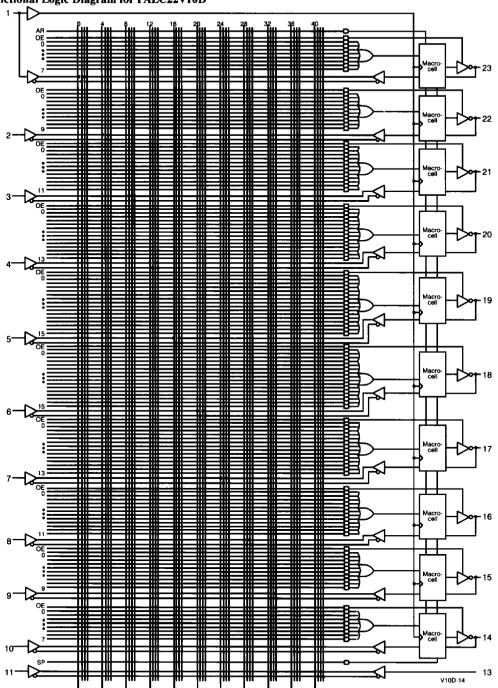


Power-Up Reset Waveform[16]





Functional Logic Diagram for PALC22V10D





Ordering Information

I _{CC} (mA)	t _{PD} (ns)	t _S (ns)	t _{CO} (ns)	Ordering Code	Package Name	Package Type	Operating Range
130	7.5	5	5	PALC22V10D-7JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
				PALC22V10D-7PC	P13	24-Lead (300-Mil) Molded DIP	1
90 1	10	6	7	PALC22V10D-10JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
				PALC22V10D-10PC	P13	24-Lead (300-Mil) Molded DIP	1
150	10	6	7	PALC22V10D-10JI	J64	28-Lead Plastic Leaded Chip Carrier	Industrial
				PALC22V10D-10PI	P13	24-Lead (300-Mil) Molded DIP	
150	10	6	7	PALC22V10D-10DMB	D14	24-Lead (300-Mil) CerDIP	Military
				PALC22V10D-10KMB	K73	24-Lead Rectangular Cerpack	
				PALC22V10D-10LMB	L64	28-Square Leadless Chip Carrier	
90	15	7.5	10	PALC22V10D-15JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
				PALC22V10D-15PC	P13	24-Lead (300-Mil) Molded DIP	
120	15	7.5	10	PALC22V10D-15JI	J64	28-Lead Plastic Leaded Chip Carrier	Industrial
				PALC22V10D-15PI	P13	24-Lead (300-Mil) Molded DIP]
120	15	7.5	10	PALC22V10D-15DMB	D14	24-Lead (300-Mil) CerDIP	Military
				PALC22V10D-15KMB	K73	24-Lead Rectangular Cerpack	
				PALC22V10D-15LMB	L64	28-Square Leadless Chip Carrier	
90	25	15	15	PALC22V10D-25JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
				PALC22V10D-25PC	P13	24-Lead (300-Mil) Molded DIP	
120	25	15	15	PALC22V10D-25JI	J64	28-Lead Plastic Leaded Chip Carrier	Industrial
				PALC22V10D-25PI	P13	24-Lead (300-Mil) Molded DIP	
120	25	15	15	PALC22V10D-25DMB	D14	24-Lead (300-Mil) CerDIP	Military
			1	PALC22V10D-25KMB	K73	24-Lead Rectangular Cerpack	
	l			PALC22V10D-25LMB	L64	28-Square Leadless Chip Carrier	1

MILITARY SPECIFICATIONS Group A Subgroup Testing

DC Characteristics

Parameter	Subgroups
V _{OH}	1, 2, 3
V _{OL}	1, 2, 3
V _{IH}	1, 2, 3
V _{IL}	1, 2, 3
I _{IX}	1, 2, 3
I _{OZ}	1, 2, 3
I_{CC}	1, 2, 3

Switching Characteristics

Parameter	Subgroups
t _{PD}	9, 10, 11
t _{CO}	9, 10, 11
ts	9, 10, 11
t _H	9, 10, 11

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